

Remarks/Arguments:

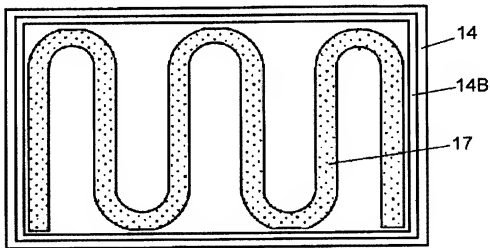
Claims 1, 13, 14 and 19 are pending in the above-identified application. Claims 1, 13, 14 and 19 are objected to. Claims 1 and 19 are rejected. Claims 2-12 and 15-18 were previously cancelled.

Rejections under 35 U.S.C. § 112

Claim 1, 13, 14 and 19 are rejected under 35 U.S.C. § 112, first paragraph. The Official Action asserts that claim 1 now requires a bulging out portion of the adhesive be formed and then a groove be formed around the holding plate such that adhesive flows into the groove such that said adhesive is prevented from hanging out. Furthermore, the Office Action asserts that the specification as originally filed does not support both a groove that adhesive flows into and a bulging out portion that is formed.

Applicants respectfully submits that as described on page 8 of the specification, lines 3-9 specifically refer to FIG. 5, a copy of which is reproduced below.

FIG. 5



In FIG. 5, element 14B is identified as the groove. While discussing the elements of FIG. 5, on page 8, lines 3-9 also state:

Adhesive 17 is applied in a serpentine shape, **as shown in Fig. 5 ... adhesive 17 is provided so that a portion of the adhesive--exposed tabs 17A** with few millimeters to few centimeters in length--comes out from the bounded edges of panel 10 and chassis member 14.

Applicant respectfully submits that FIG. 5 discloses the use of groove 14B. Furthermore, the specification discloses the creation of exposed tabs 17A while discussing FIG. 5 on page 8, lines 3-9. Therefore, Applicant respectfully submits that the specification supports the use of both a groove that the adhesive flows into and a bulging out portion that is formed. Accordingly, Applicants respectfully request withdrawal of the rejection under 35 U.S.C. § 112, first paragraph.

Claim Rejections under 35 U.S.C. § 103

Claims 1 and 19 are rejected under 35 U.S.C. § 103(a), as being unpatentable over Japanese Patent Application Publication 2002/268577 (hereinafter "Kaneko") in view of U.S. Patent No. 6,496,373 (hereinafter "Chung") in further view of U.S. Patent Publication No. 2002/0193035 (hereinafter "Wei"). It is respectfully submitted, however, that the claims are patentable over the art of record for the reasons set forth below.

Kaneko discloses a plasma display panel 1 that includes a front glass substrate 1A and a back glass substrate 1B. A chassis 3 is secured to a back surface of the plasma display panel 1 with a plurality of double faced adhesive tapes 50. An edge 50A of double faced adhesive tape 50 protrudes beyond the ends of the plasma display panel 1 and chassis 3. Chung describes a heat dissipating arrangement that includes a heat dissipating element 20 and a mechanical fastener 30. A plurality of components 10 are clamped by the mechanical fasteners 30. A melt-flowable thermal interface 100 is disposed between the components 10 and the heat dissipating element 20. Wei describes a panel supply system that includes a panel 200 and a lamination panel 204. The lamination plate 204 includes a trench 206 formed at an edge thereof. A sealing agent 208 is created on an OEL display 202 between the panel 200 and the lamination plate 204. A pressure is applied to the lamination plate 204 and the excess of the sealing agent 208 flows into the trench 206.

Applicant's invention as recited in claim 1 includes a feature which is neither disclosed nor suggested by the art of record, namely:

... applying heat and pressure to the panel and the holding plate for forming a bulging-out portion of the adhesive bulging out from between the panel and the plate ... forming a groove around the holding plate ...

This feature is found in the originally filed application at page 8, lines 3-9 and FIG. 5.
No new matter has been added.

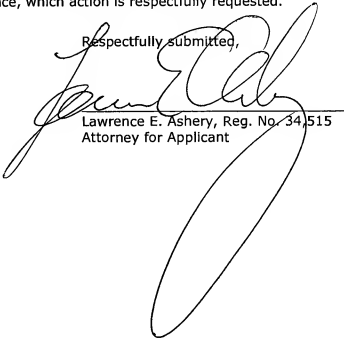
Applicant respectfully submits that the cited prior art alone or in combination does not disclose or suggest each element of claim 1. As acknowledged in the Office Action, Kaneko, in view of Chung, in further view of Wei would fail to produce the claimed patented invention. The purpose of the groove in Wei is to accept the flowed portion of the adhesive to prevent it from leaking to the outside of the substrate. Therefore, Applicant respectfully submit that the groove disclosed in Wei would not allow the formation of a "bulging-out portion" as recited in Applicant's claim 1. In fact, Wei teaches against the creation of these tabs by disclosing a groove that accepts the flowed portion of adhesive and prevents it from leaking to the outside of the substrate as disclosed in paragraphs 20-27. Therefore, Applicant respectfully submits that Kaneko in view of Chung, in view of Wei fails to disclose each and every limitation of claim 1.

Accordingly for the reasons set forth above, claim 1 is patentable over the art of record. Claims 13, 14 and 19 include all the features of claim 4 from which they depend. Thus, claims 13, 14 and 19 are also patentable over the art of record for the reasons set forth above.

Conclusion

In view of the foregoing remarks and amendments, Applicant respectfully asserts that the claims are in condition for allowance, which action is respectfully requested.

Respectfully submitted,



Lawrence E. Ashery, Reg. No. 34,515
Attorney for Applicant

ZF/sh

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P.O. Box 980
Valley Forge, PA 19482
(610) 407-0700

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